

AMENDMENTS TO THE CLAIMS

The listing of claims below replaces all prior versions of claims in the application.

1. (Currently amended) A copper foil for fine pattern printed circuits comprising untreated copper foil roughening treated on its surface,

wherein said untreated copper foil before roughening treatment is an electrodeposited copper foil having a surface roughness in terms of 10-point average roughness Rz of not more than 2.5 μm and a minimum distance between peaks of rough pyramid of at least 5 μm , and at least one surface of said untreated copper foil is roughening treated by being formed with a burnt plating layer by burnt plating of copper containing at least one of molybdenum, iron, cobalt, nickel and tungsten.

2. (Currently amended) A copper foil for fine pattern printed circuits comprising untreated copper foil roughening treated on its surface,

wherein said untreated copper foil before roughening treatment is an electrodeposited copper foil having a surface roughness in terms of 10-point average roughness Rz of not more than 2.5 μm , a minimum distance between peaks of rough pyramid of at least 5 μm , and crystal grains of an average particle size of not more than 2 μm exposed at the surface, and at least one surface of said untreated copper foil is roughening treated by being formed with a burnt plating layer by burnt plating of copper containing at least one of molybdenum, iron, cobalt, nickel and tungsten.

3. (Canceled)

4. (Currently amended) A copper foil for fine pattern printed circuits as set forth in ~~claim~~
~~3~~ claim 1, wherein said burnt plating layer is formed over it with a copper plating layer.

5. (Currently amended) A copper foil for fine pattern printed circuits as set forth in ~~claim~~
~~3~~ claim 1, wherein said burnt plating layer is provided over it with at least one layer of a nickel
plating layer, nickel alloy plating layer, zinc plating layer, zinc alloy plating layer, cobalt plating
layer, cobalt alloy plating layer, chrome plating layer, and chrome alloy plating layer and is
~~further~~ optionally provided over that with a layer formed by treatment by chromate or a silane
coupling agent ~~according to necessity~~.

6. (Currently amended) A copper foil for fine pattern printed circuits as set forth in claim
4, wherein said burnt plating layer or said copper plating layer is provided over it with at least
one layer of a nickel plating layer, nickel alloy plating layer, zinc plating layer, zinc alloy plating
layer, cobalt plating layer, cobalt alloy plating layer, chrome plating layer, and chrome alloy
plating layer and is ~~further~~ optionally provided over that with a layer formed by treatment by
chromate or a silane coupling agent ~~according to necessity~~.

7-9. (Canceled)

10. (New) A copper foil for fine pattern printed circuits as set forth in claim 2, wherein said burnt plating layer is formed over it with a copper plating layer.

11. (New) A copper foil for fine pattern printed circuits as set forth in claim 2, wherein said burnt plating layer is provided over it with at least one layer of a nickel plating layer, nickel alloy plating layer, zinc plating layer, zinc alloy plating layer, cobalt plating layer, cobalt alloy plating layer, chrome plating layer, and chrome alloy plating layer and is optionally provided over that with a layer formed by treatment by chromate or a silane coupling agent.

12. (New) A copper foil for fine pattern printed circuits as set forth in claim 10, wherein said burnt plating layer or said copper plating layer is provided over it with at least one layer of a nickel plating layer, nickel alloy plating layer, zinc plating layer, zinc alloy plating layer, cobalt plating layer, cobalt alloy plating layer, chrome plating layer, and chrome alloy plating layer and is optionally provided over that with a layer formed by treatment by chromate or a silane coupling agent.